

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Zvi Or-Bach</td> <td>01/09/2013</td> </tr> <tr> <td>Ze'ev Wurman</td> <td>01/10/2013</td> </tr> </tbody> </table>		Name	Execution Date	Zvi Or-Bach	01/09/2013	Ze'ev Wurman	01/10/2013
Name	Execution Date						
Zvi Or-Bach	01/09/2013						
Ze'ev Wurman	01/10/2013						
RECEIVING PARTY DATA							
Name:	Monolithic 3D Inc.						
Street Address:	3555 Woodford Drive						
City:	San Jose						
State/Country:	CALIFORNIA						
Postal Code:	95124						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12904108</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12904108		
Property Type	Number						
Application Number:	12904108						
CORRESPONDENCE DATA							
Fax Number:							
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Email:	Brian@Monolithic3D.com						
Correspondent Name:	Brian Cronquist						
Address Line 1:	3555 Woodford Drive						
Address Line 4:	San Jose, CALIFORNIA 95124						
ATTORNEY DOCKET NUMBER:	MONOLITHIC 3D-004						
NAME OF SUBMITTER:	Brian Cronquist						
Total Attachments: 2 source=Monolithic3D-004-ZW2_assignment_Zvi_s#page1.tif source=Monolithic3D-004-ZW2_assignment_Zeev_s#page1.tif							

OP \$40.00 12904108

ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in San Jose, California;** have made a certain invention, and executed United States Patent Application entitled:

3D Semiconductor Device Including Field Repairable Logics

as described in U.S. Patent Application Serial No. 12/904,108, issuing as US-8,362,800, and filed on October 13, 2010; and

Whereas, Monolithic 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

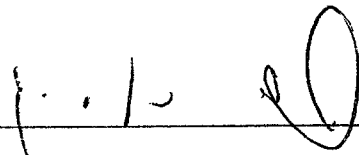
Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 1-9-2013

		
(Zvi		Or-Bach)
First Name	Middle Initial	Last Name

ZWZ

ASSIGNMENT

Whereas, I, **Ze'ev Wurman** (hereinafter referred to as **Assignor(s)**), residing in **Palo Alto, California**; have made a certain invention, and executed United States Patent Application entitled:

3D Semiconductor Device Including Field Repairable Logics

as described in U.S. Patent Application Serial No. 12/904,108, issuing as US-8,362,800, and filed on October 13, 2010; and

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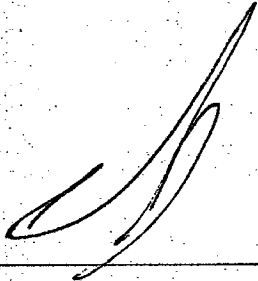
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Signed and Sealed:

INVENTOR:

DATE on 1/10/13



(Ze'ev Wurman)
 First Name Middle Initial Last Name